

ENABLING NEXT-GEN POWER BUSBAR SOLUTIONS

Liquid Cooled Power Busbar Assembly from TE Connectivity (TE) and Cooler Master

In partnership with Cooler Master, TE is enabling the next-gen power busbar solutions empowering the AI evolution. As rack level power requirements continue to increase, power busbar capacities need to follow suit. Using liquid cooled infrastructures to cool the power busbars enables higher current capacities, while maintaining lower temperatures.



Manifold Assembly

Circulates the liquid from the CDU to the liquid cold plate



Liquid Cooled Power Busbar Assembly

Enables higher power distribution at lower temperatures

